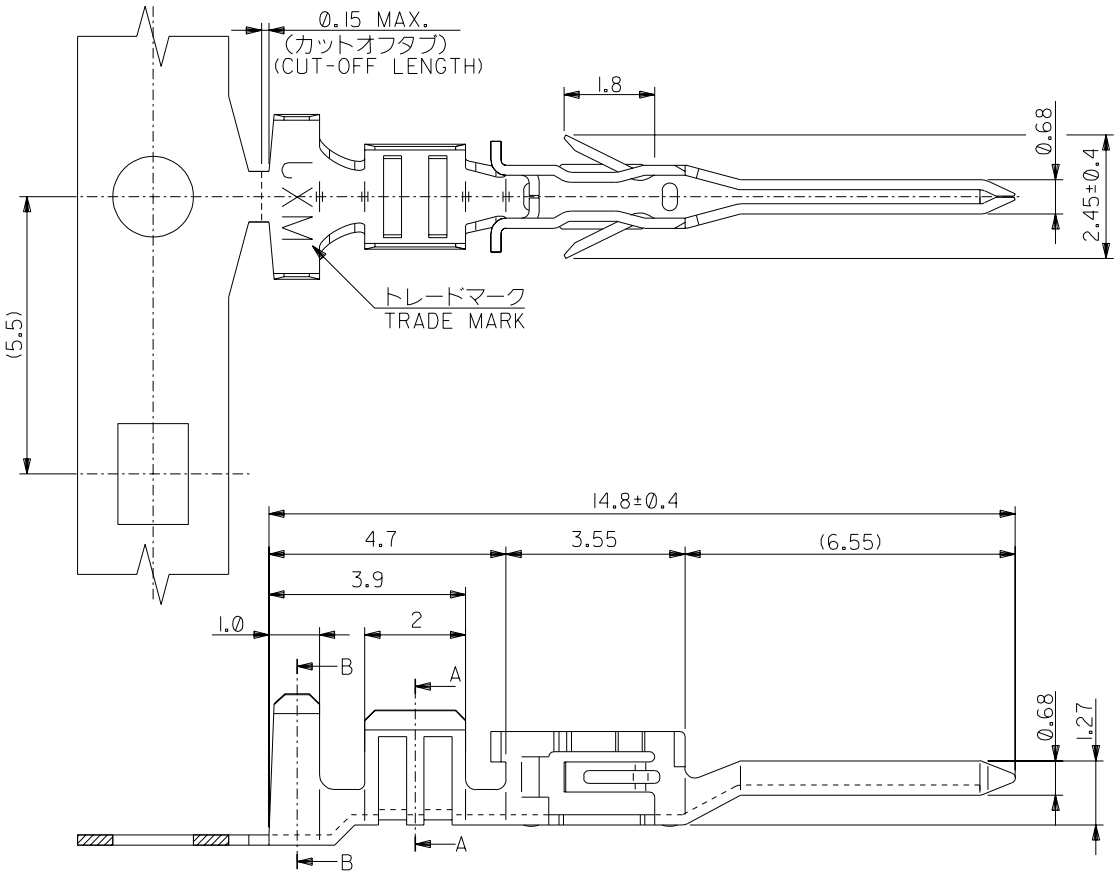
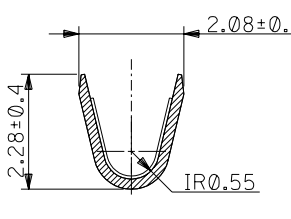
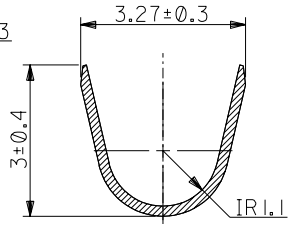




SECTION A-A



SECTION B-B

注記
NOTES

1. 材質
MATERIAL
りん青銅　(板厚：0.2)
PHOSPHOR BRONZE (THICKNESS : 0.2)

2. メッキ仕様
TERMINAL PLATING
接点部　：　金メッキ 0.25 μmMIN.
CONTACT AREA : GOLD 0.25 μm MIN.
圧着部　：　半田メッキ 1.0μm MIN.
CRIMP AREA : TIN-LEAD 1.0 μm MIN.
下地メッキ　：　ニッケルメッキ 2 μm MIN.
UNDER PLATE : NICKEL 2 μm MIN.

3. 適用電線：UL1007，AWG #18～22
APPLICABLE WIRE RANGE : UL1007, AWG #18～22

4. 被覆外径　：ø2.2 MAX.
INSULATION EXTERNAL DIA : ø2.2 MAX.

5. 適用ハウジング：51233-**** , 51234-****
APPLICABLE HOUSING : 51233-**** , 51234-****

バラ状 LOOSE	56117-8390	56117-8***
連鎖状 CHAIN	56117-8290	
端子形状 TERMINAL CONFIGURATION	MATERIAL No.	MODEL NO.

DO NOT SCALE DRAWING

	EC NO.	DRWN	CH'K	APPR
REV	0	J2003-3238	S.AKIYAMA	J.MIYAZAWA / YO.ITO
DESCRIPTION	RELEASED	'03/06/20		

MATERIAL 材料: 注記参照 SEE NOTES
FINISH 仕上げ
WIRE RANGE 適用電線範囲
INS. RANGE 被覆外径

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差

10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

SCALE ~ | DESIGN UNITS ☒mm ☐INCH | THIRD ANGLE PROJECTION | DIMENSIONS: ☐mm/INCH ☐INCH/mm ☒mm ONLY | SHT | REV | REVISE ON CAD ONLY

DRAWN BY & DATE: S.Akiyama '03/01/29
CHECKED BY & DATE: J.Miyazawa
APPROVED BY & DATE: Y.Ito

TITLE: COMPACT ROBOT CONN. (CRC) CRIMP PIN (SEQUENTIAL TYPE)

molex MOLEX INCORPORATED

CAD FILENAME: SD-56117-001.S01 | MATERIAL NO.: SEE CHART | DRAWING NO.: SD-56117-001 | SHEET NO.: 1 OF 1

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SIZE B